

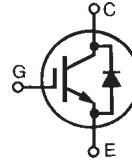
IGBT with Diode

IXGR 50N60A2U1

$$\begin{aligned} V_{CES} &= 600 \text{ V} \\ I_{C25} &= 75 \text{ A} \\ V_{CE(sat)} &= 1.7 \text{ V} \end{aligned}$$

Low Saturation Voltage IGBT with
Low Forward Drop Diode
Electrically Isolated Mounting Tab

Preliminary Data Sheet



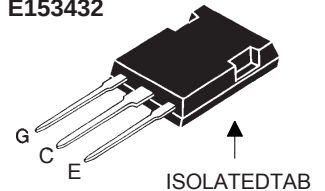
Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_J = 25^\circ\text{C}$ to 150°C	600	V
V_{CGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GE} = 1 \text{ M}\Omega$	600	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ\text{C}$ (limited by leads)	75	A
I_{C110}	$T_C = 110^\circ\text{C}$	50	A
I_{F110}	$T_C = 110^\circ\text{C}$ (50N60A2U1 Diode)	25	A
I_{CM}	$T_C = 25^\circ\text{C}$, 1 ms	200	A
SSOA (RBSOA)	$V_{GE} = 15 \text{ V}$, $T_{VJ} = 125^\circ\text{C}$, $R_G = 10 \Omega$ Clamped inductive load @ $V_{CE} \leq 600 \text{ V}$	$I_{CM} = 80$	A
P_C	$T_C = 25^\circ\text{C}$	200	W
T_J		$-55 \dots +150$	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		$-55 \dots +150$	$^\circ\text{C}$
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$
F_C	Mounting Force	22..130/5..29	N/lb
V_{ISOL}	50/60 Hz, RMS, $t = 1$ minute $I_{SOL} = 1 \text{ mA}$, $t = 1$ s	2500 3000	V~ V~
Weight		4	g
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		Min.	Typ.	Max.
$V_{GE(th)}$	$I_C = 250 \mu\text{A}$, $V_{CE} = V_{GE}$	3.0		5.0
I_{CES}	$V_{CE} = V_{CES}$ $V_{GE} = 0 \text{ V}$			650 μA 5 mA
I_{GES}	$V_{CE} = 0 \text{ V}$, $V_{GE} = \pm 20 \text{ V}$			± 100 nA
$V_{CE(sat)}$	$I_C = 50 \text{ A}$, $V_{GE} = 15 \text{ V}$ Note 1		1.3	1.7

ISOPLUS247(IXGR)



E153432



G = Gate C = Collector
E = Emitter

Features

- Low on-state voltage IGBT and anti-parallel diode in one package
- High current handling capability
- MOS Gate turn-on for drive simplicity

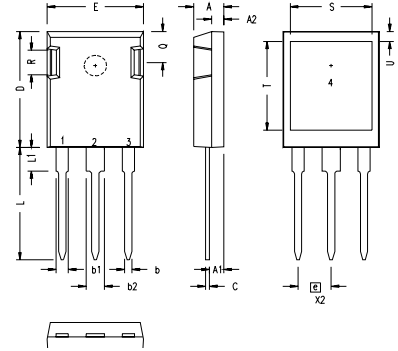
Applications

- Lighting controls
- Heating controls
- AC/DC relays

Advantages

- Space savings (two devices in one package)
- Easy to mount with 1 screw or spring clip

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		Min.	Typ.	Max.
g_{fs}	$I_C = 50\text{ A}; V_{CE} = 10\text{ V}$, Note 1	40	55	S
C_{ies}	$V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$		3500	pF
C_{oes}			400	pF
C_{res}			50	pF
Q_g	$I_C = 50\text{ A}, V_{GE} = 15\text{ V}, V_{CE} = 0.5\text{ V}_{CES}$		140	nC
Q_{ge}			23	nC
Q_{gc}			44	nC
$t_{d(on)}$	Inductive load, $T_J = 25^\circ\text{C}$ $I_C = 50\text{ A}, V_{GE} = 15\text{ V}$ $V_{CE} = 480\text{ V}, R_G = R_{off} = 5.0\ \Omega$		20	ns
t_{ri}			25	ns
$t_{d(off)}$			410	ns
t_{fi}			260	ns
E_{off}			3.5	mJ
$t_{d(on)}$	Inductive load, $T_J = 125^\circ\text{C}$ $I_C = 50\text{ A}, V_{GE} = 15\text{ V}$ $V_{CE} = 480\text{ V}, R_G = R_{off} = 5.0\ \Omega$		20	ns
t_{ri}			25	ns
E_{on}			1.0	mJ
$t_{d(off)}$			720	ns
t_{fi}			510	ns
E_{off}			7.7	mJ
R_{thJC}			0.15	0.62 K/W
R_{thCK}				K/W

ISOPLUS247 Outline


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b1	.075	.084	1.91	2.13
b2	.115	.123	2.92	3.12
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
E	.620	.635	15.75	16.13
e	.215 BSC		5.45 BSC	
L	.780	.800	19.81	20.32
L1	.150	.170	3.81	4.32
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83
S	.520	.540	13.21	13.72
T	.620	.640	15.75	16.26
U	.065	.080	1.65	2.03

- 1 - GATE
 2 - DRAIN (COLLECTOR)
 3 - SOURCE (EMITTER)
 4 - NO CONNECTION

NOTE: This drawing will meet all dimensions requirement of JEDEC outline TO-247AD except screw hole.

Reverse Diode (FRED)		Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
Symbol	Test Conditions	min.	typ.	max.
V_F	$I_F = 50\text{ A}, V_{GE} = 0\text{ V}$, Note 1			1.6 V
R_{thJC}				0.95 K/W

Note 1: Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585
4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692
4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2

Fig. 1. Output Characteristics
@ 25 °C

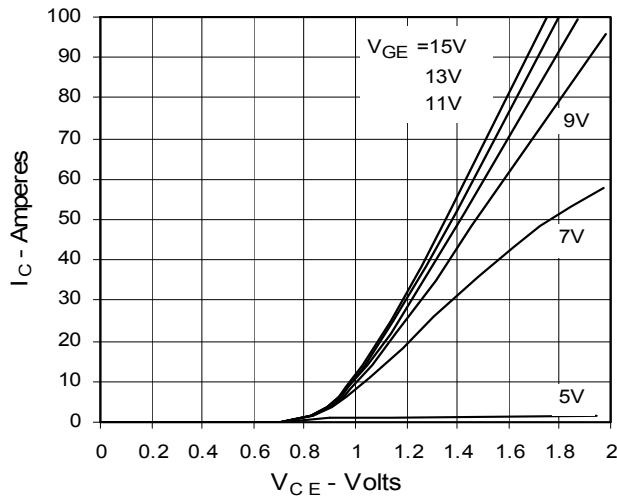


Fig. 2. Extended Output Characteristics
@ 25 °C

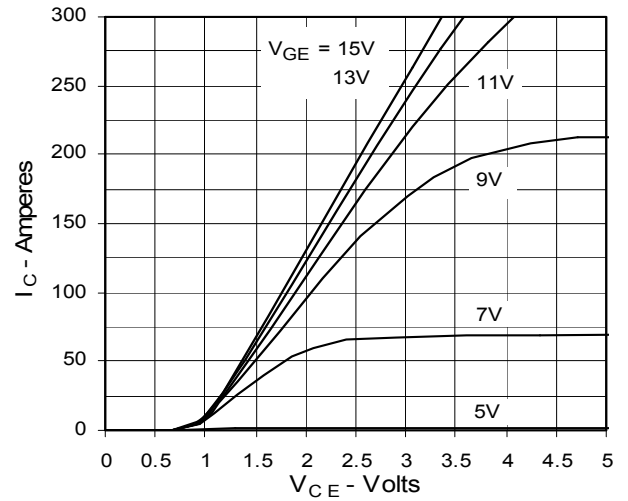


Fig. 3. Output Characteristics
@ 125 °C

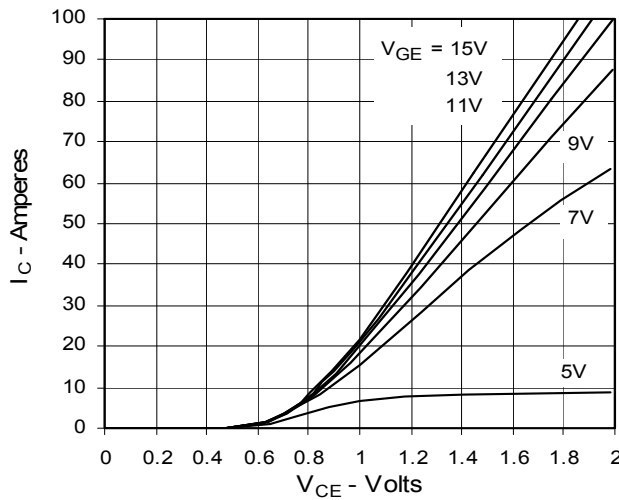


Fig. 4. Dependence of $V_{CE(sat)}$ on Temperature

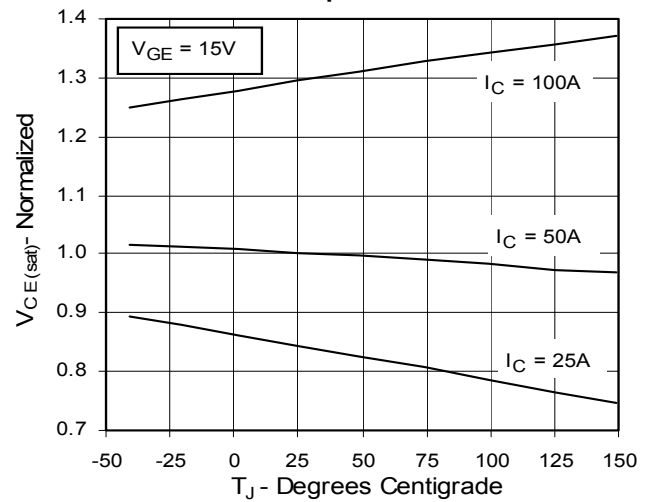


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter voltage

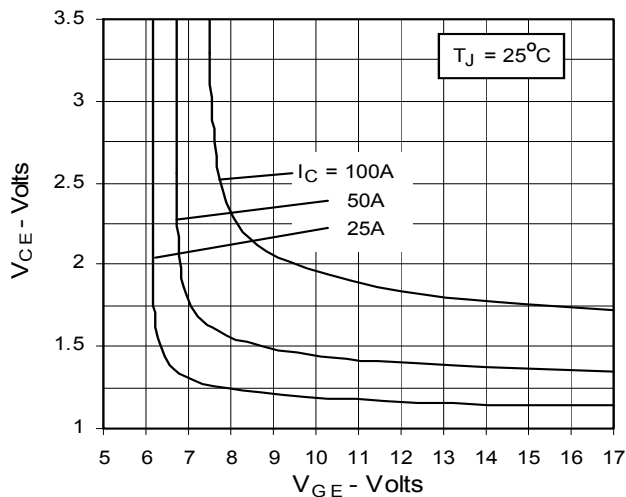


Fig. 6. Input Admittance

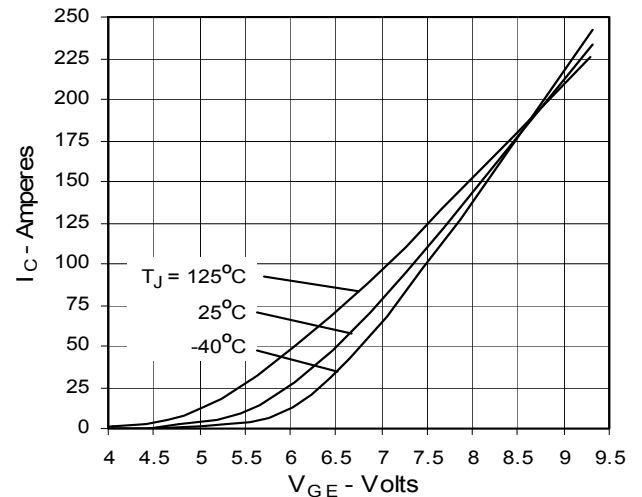


Fig. 7. Transconductance

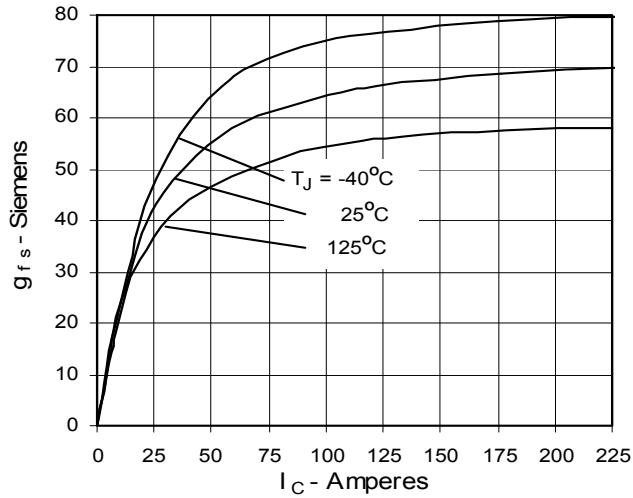
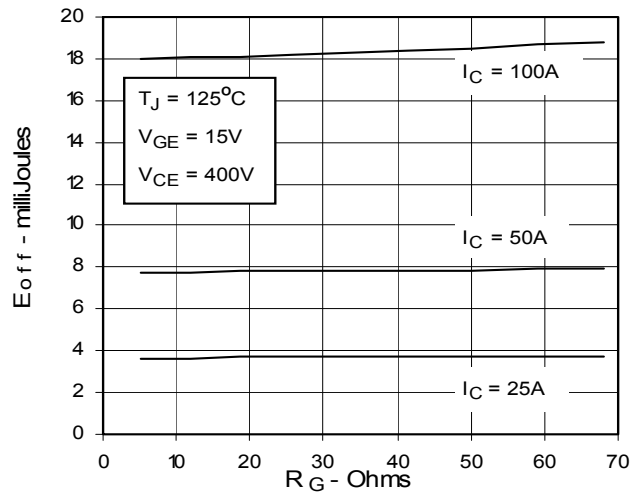
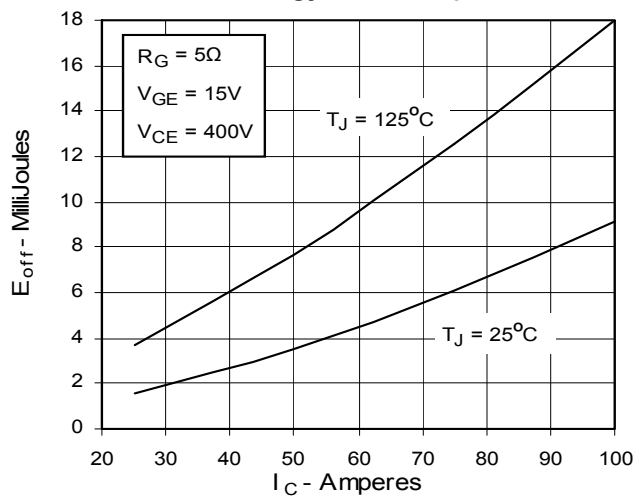

Fig. 8. Dependence of Turn-off Energy Loss on R_G

Fig. 9. Dependence of Turn-Off Energy Loss on I_C


Fig. 10. Dependence of Turn-off Energy Loss on Temperature

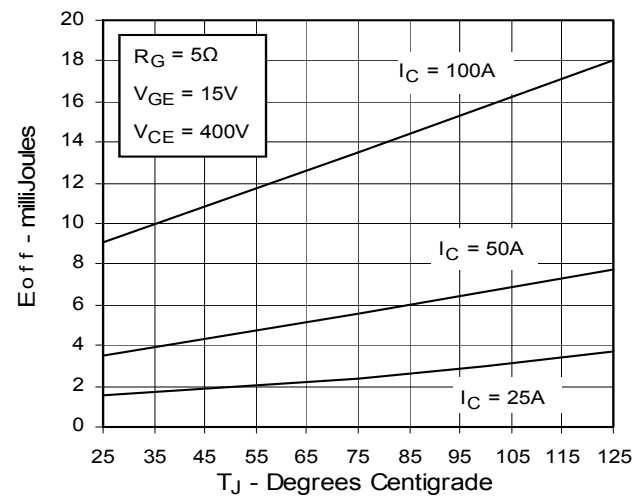
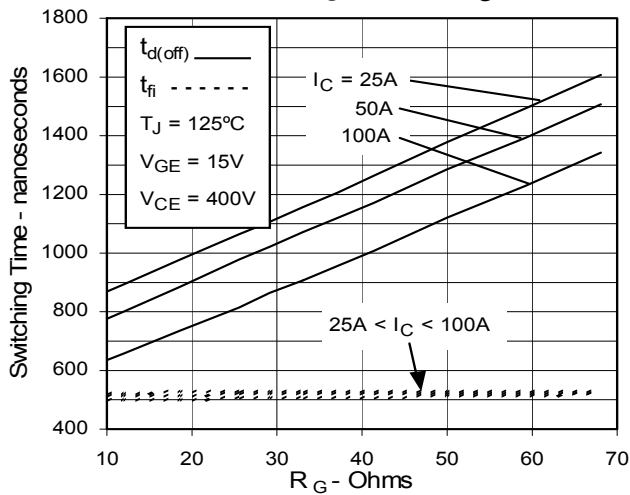
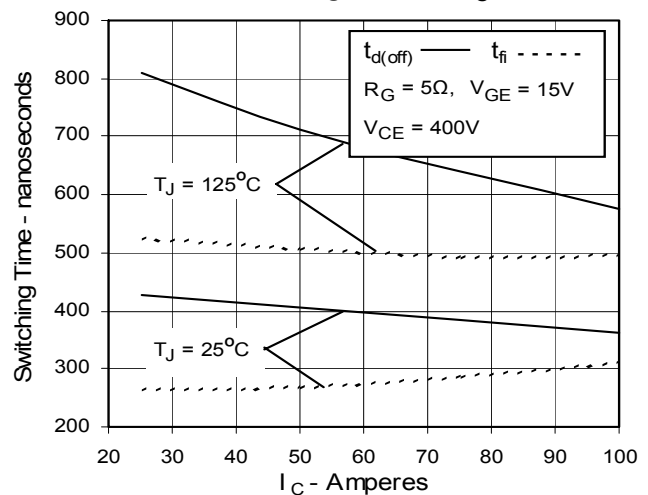

Fig. 11. Dependence of Turn-off Switching Time on R_G

Fig. 12. Dependence of Turn-off Switching Time on I_C


Fig. 13. Dependence of Turn-off Switching Time on Temperature

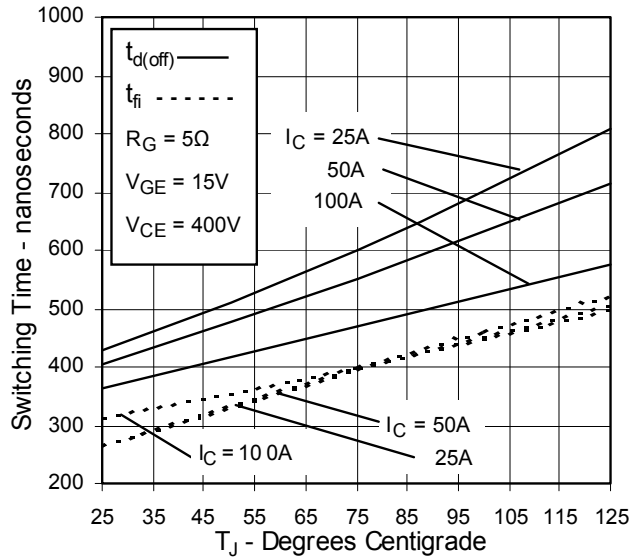


Fig. 14. Gate Charge

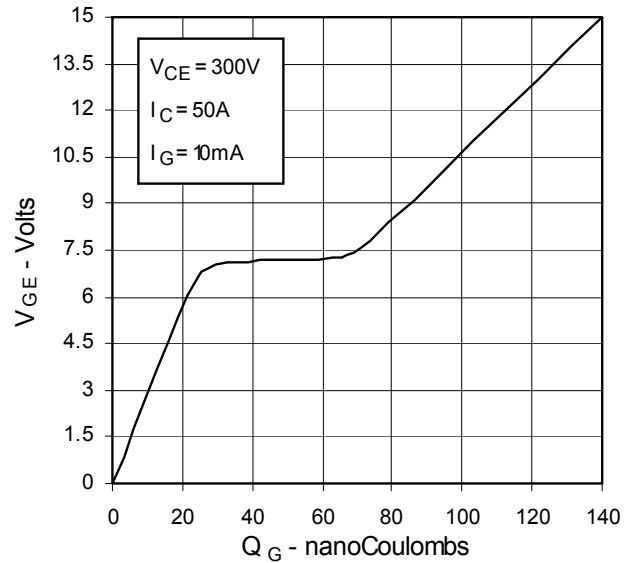


Fig. 15. Capacitance

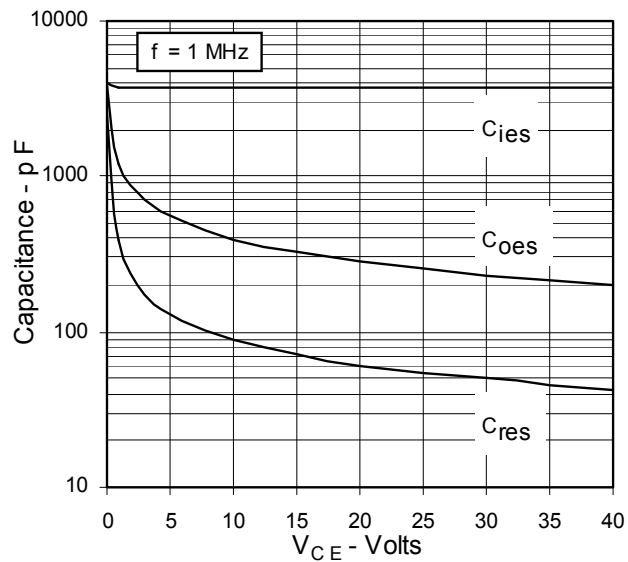


Fig. 16. Reverse-Bias Safe Operating Area

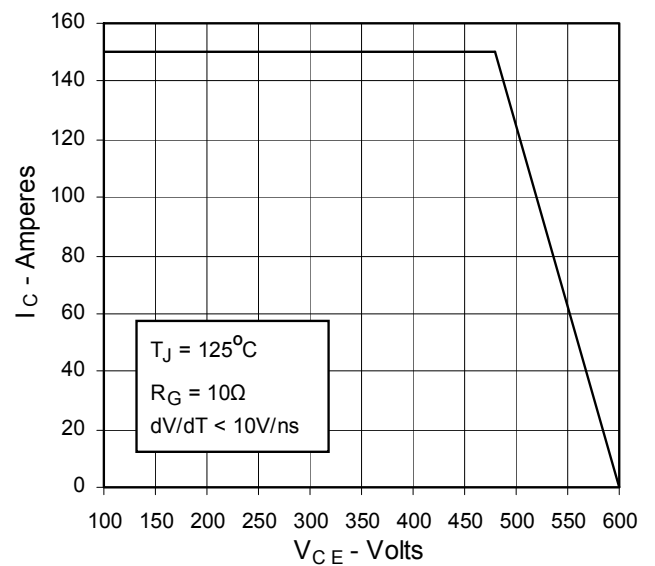


Fig. 17. Maximum Transient Thermal Resistance

